



A Survey Paper on Design Implementation of SRAM Cell Based on Low Power Consumption

Kunal Geed¹, Prof. Amit Thakur²

¹M. Tech. Scholar, Department of EC, SVCST, Bhopal, India

²Asst. Professor, Department of CSE, SVCST, Bhopal, India

Abstract: In the field of VLSI research in electronic circuitry. Memory is the basic demand of most electronic devices. These memory components are designed specifically using a CMOS transistor. When we talk about CMOS power, the area and speed of each transistor is a big deal. But we know there is a trade-off between these three things. Engineers and researchers are still working on these questions. Various methods have been used to reduce water leakage within the designed circle. As a result, the praise capacity in the SRAM cell is reduced and it works better. The computing power in the SRAM bitcell is reduced and its performance is better. The designed SRAM bitcell showed nearly 3 times the purging power of the SRAM 6T bitcell. Read and write times access to SRAM bitcell intended to increase and decrease volume. RAM is used as main memory for small value devices that do not have a cache. Therefore, the construction of memory using an optimized SRAM cell in terms of process parameters, i.e. power consumption, quantity, area and delay, is a domain of concern. Critical analysis and the same are presented in a functional way. The SRAM 6T to 10T was found to have better performance in terms of power consumption and power model, but has a higher access time than other existing SRAM components when compared to the results obtained in mode CMOS with Micro wind Tools.

Keywords: VLSI, Memory, SRAM, DRAM, Power Consumption, Power Reduction, Power Dissipation, CMOS Technology, Delay.

I. INTRODUCTION

SRAM (Random Access Memory) can also be a type of random semiconductor memory that uses latches or latches to store data, so that the data in its storage is permanent as long as its power is used. Another source of random access is DRAM (Random Random Access Memory), as well as MOS semiconductor memory, which uses a capacitor and a transistor to store data. SRAM and DRAM are memory modifiers. SRAM is more popular despite its high cost and low data collection compared to DRAM due to its speed i.e. cell data is often read at the speed of SRAM compared to DRAM. In addition, SRAM does not require occasional refresh like DRAM. Thus, SRAM can be an option for developers in applications where high speeds may be required, so the cost of the cell is as high as in the case of cache memory. In modern times when battery operated devices have become commonplace, blackouts and zones have become major causes of the need for smaller power generating devices. Every day, the size of the connection is increasing to satisfy the small number of small chips by small chips. This technological scale causes instability of SRAM cellular functions. Normal SRAM cartridges suffer from various low tech issues like leakage current, read stability, etc. to understand the design that can work on small technologies, different SRAM cells are developed. As there is a compromise between the different parameters of the SRAM cell, it is therefore not possible to realize all the components during the same design. Thus, different configurations according to different needs in many applications are optimized by considering 1 or more parameters. This article discusses the different types of SRAM cells that carry a unique number of transistors and have some advantages over smaller ones, so the advantages and disadvantages of different SRAM cells are different. RAM dominates most of the system on chip (SoC) and dominates system performance and control. Especially in bioelectronics and other emerging applications, low power and low SRAMs are required to expand the operating system with less power. Consequently, the design of low voltage and low power SRAM circuits [1] is constantly increasing. Two factors are important for the design of the SRAM cell: the surface area of the cell and therefore the stability of the cell. The two are interrelated since the design of the cell for optimum stability always requires the size of the cell area. As the device size continues to decrease, increasing current points, system changes, and random variations lead to errors. In addition, typing errors can occur due to the difficulty in maintaining the power value of the device in the ground area. The best way to improve SNM drive read is to remove cell storage nodes from the current read row, so that the SNM drive can contain the SNM. To strengthen the WM and write operation, the maximum power is used to write the capacitance of transistor [2] and / or write the help circuits to the extra power and extra control value. Several SRAM cell systems that depend on soil function are presented in the literature. This article examines the latest types of SRAM models that address stability and reliability issues. The rest of the document is structured as follows. Section 2 reviews the different SRAM models. Section 3 includes the comments and section 4 concludes the article [1].

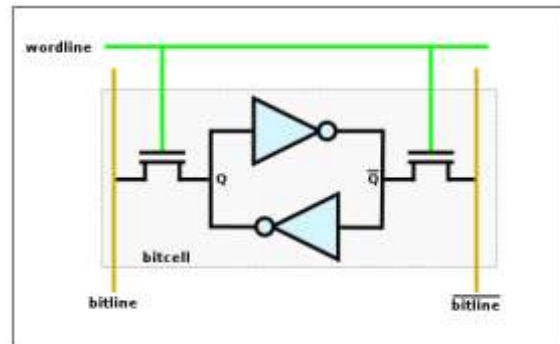


Fig.1 basic building block of SRAM memory

The SRAM bitcell is the real building block of SRAM memory. The cell keeps the same value as long as there is current. The two access points to the cell are called bit lines (BL). The bit lines contain the value of the stored bit and its precision. Two incoming transistors are on bit rows to enable and disable access to stored data for read and write activities. The signal that controls the input transistor is called the word line (WL).

II.LITERATURE REVIEW

Various research activities have been carried out and are continuing every day to increase the reliability of the SRAM virus in order to overcome the trade-off between surface area, speed and power. A few of the research papers were reviewed and the activities carried out in the papers are listed below.

1) Mahendra Kumar and Kailash Chandra [4] suggest that data retention and leakage are now a major concern in today's CMOS technology. so get the higher noise side with the best performance new SRAM cartridges are introduced. In most cases, the work of reading and writing the cell is not put aside for additional noise. In large-size RAM memory chips, reduced performance is important to detect short-term, low-cost reliability, as it allows the temperature of the plastic. Thus, different circuit breaker technologies are developed based on the reduction of the load capacity, the working capacity and the current intensity. As a result, the working capacity of each generation is reduced despite the high output power, increased chip size and improved access. SRAM technology evolves towards high volume, high speed and low power. The maximum quantity and the best speed are obtained by scale. Reducing the actual oxide flow rate is important to understanding the high rate of hold time maintenance. Electricity consumption is reduced by reducing electricity supply and creating a navigation system. New technologies, such as Cu interconnects and small K 'dielectrics have been introduced for faster operation.

2) Simran Kaur and Ashwani Kumar [5] have suggested power failures during the process of writing to CMOS T CMOS SRAM six-T as well as reading. In its research work, the SRAM cell is shown in figure 11, it will include an additional transistor which can control the overall force during the writing and skimming process and improve the overall force resulting in reduced dissipation of the l 'equipment. Here, during this project, they are targeting an electricity shortage, as the power supply is also called the power supply. The circuit is defined using 130nm technology which has q to generate a power of 1.5 volts and the grid power is 0.40 volts. The results were compared to a standard SRAM 6T cell which is also described in this review with the same technology. This small modified cell consumes less power, the average saves 54% compared to the SRAM cell.

3) VineshSrinivasan, VarshadVenkatraman.R, Senthilkumar.KK [3] suggest that the amount of power consumed during the operation of a regular SRAM 6T cell results in limited read and write capacity of the cell, thus causing confusion - confusion of the end. The Schmitt cell model solves this problem by providing an efficient response mechanism to adjust the correct switching of the inverter according to the input voltage. ST SRAM molecules have an efficient response mechanism to deal with variations in PVT, with the interaction with CNFET shown in Figure .10 providing unique electrical properties in the nanometer range, proving to be suitable for future cells. SRAM. When changing input node, the feedback transistor stores 1 at the output node by increasing the voltage source of NCFET N1. This provides the best replacement for the inverter. During entry time, the entry response system refers to logic that provides the best transfer characteristics for the text function. The results transfer changing characteristics with respect to cell input and improve the read and write accuracy of SRAM cells

4) Mo Maggie Zhang [1] suggests that the performance simulations of SRAM 6, 7 and 8T topologies are shown in Figures 1, 2 and 3. As process technology advances, the speed of SRAMs will increase. , but I Businesses grow. be very sensitive to jitter, which disturbs the direct noise (SNM) of SRAM cells. thanks to stress and stability, a two-port model that implements a stress-free read function like that seen in the 7T and 8T cell process might be most useful at the end of the SRAM cell implementation of the daytime. Although the 7T and 8T cell processes ended with a 13% and 30% increase



respectively reported, these two topologies leave the best cell stability due to the unreadable function, which is useful as process technology is in decline.

5) Nakkala Suresh and Dr. VangalaPadmaja [2] strongly recommend Schmitt to design the SRAM source that is suitable for low power application applications in Figures 7 and 8. This response system is generally effective for nanoscale technology in the field. resistance, low performance of SRAM. The results of experimental simulations at Mentor Graphics EDA were analyzed with TSMC-250nm, TSMC-350nm technology. nanometric range, proving to be an ideal combination for future SRAM cells. When changing input node, the feedback transistor stores 1 at the output node by increasing the voltage source of NCFET N1. This provides the best replacement for the inverter. During entry time, the entry response system refers to logic that provides the best transfer characteristics for the text function. The results transfer changing characteristics with respect to cell input and improve the read and write accuracy of SRAM cells.

6) Shilpi Birla1 and. al (2011) analyzed the 8T static random access memory cell at 65nm process technology is shown in Figure ..2. This topology was originally developed for high performance RAM and was developed to be more effective and efficient than the size of the power supply. The write process is carried out through the WWL, WBL and WBLX ports, while the single read function is implemented through the RWL and RBL ports. The RBL charges to the best of each read cycle and recharges during the write cycle. At this cell time, cell writing and thin port are separated as opposed to traditional 6T cell. The SNM reading problem has been eliminated and the vertical size of the 6T RAM is optimized for improved text without the RSNM trade. This causes the reduction of the inadequate readings to zero and therefore the inch on the reading line is drastically reduced. Vdd is that the virtual provides cross nodes with inverters and reduces its power when writing to weaken the PMOS loading device and alleviate the low voltage write problem. Because all of the bits, lines are written and skimmed correctly. time, Vdd divides into parallel lines of memory cells.

III.CONCLUSION

Variations in static RAM transistor topologies have been reviewed. Analysis with a 6T, 7T, 8T and 9T SRAM architecture. SRAM activities are studied in different buildings. Normal 6Ts have the lowest transistor values and make up the largest area. The standard 6T has the lowest transistor ratings and offers the same stability as the best zone. As the number of transistors increases, the SRAM area increases. The circuit voltage is increased to a voltage lower than 1.8V compared to that of a standard SRAM 6T cell, but the surrounding PDP is significantly reduced at all voltages. While a significant reduction is seen in both lead time and power consumption compared to the SRAM 8T. The designed circle also has some flexibility to minimize the possibility of a weak point error. This article focuses on the design techniques used to construct SRAM cells. SRAM occupies the highest percentage in integrated circuits, which finds its application in high speed devices as well as in multi-port devices.

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